

HT7000 Thermally Conductive Gap Filler

BENEFITS AND FEATURES

- High thermal performance
- Low contact resistance
- Easily dispensable and reworkable
- High compressibility for low stress applications
- Reliable thermal performance
- No pump out and cracking risk



OVERVIEW

Honeywell HT7000 Gap Filler provides an effective thermal properties and high conformability with its high compressibility. It is formulated to deliver high dispense rates for improved productivity, long-term reliability performance and easy reworkable. It is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing.

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Power supplies & semiconductors
- Memory & power modules
- Power electronics

Property	HT7000	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Thermal Conductivity (W/m·K)	7.0	ASTM D5470
Thermal Impedance ($^{\circ}\text{C} \cdot \text{cm}^2/\text{W}$)	1.41	ASTM D5470 1mm@10psi
Dispense Rate (g/min)	>14	30cc EFD syringe/ no tip/ 0.100" orifice/ @0.6Mpa
Specific Gravity	3.45	ASTM D792
Out Gassing (TML)	<0.05%	HON Internal
Color	Dark Red	Visual

Honeywell Electronic Materials

USA: 1-509-252-2102
 China: 400-840-2233
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593

www.electronicmaterials.com

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